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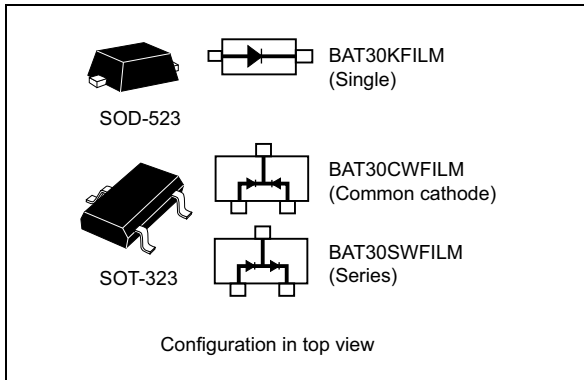
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## Small signal Schottky diodes

Datasheet - production data


**Description**

The BAT30 series uses 30 V Schottky barrier diodes encapsulated in SOD-523 or SOT-323 packages.

This device is specially suited for switching mode applications needing low forward voltage drop diodes.

**Features**

- Very low conduction losses
- Negligible switching losses
- Low forward and reverse recovery times
- Extremely fast switching
- Surface mount device
- Low capacitance diode
- ECOPACK<sup>®</sup>2 and RoHS compliant component

**Table 1. Device summary**

Symbol	Value
$I_F$	300 mA
$V_{RRM}$	30 V
C (typ.)	14 pF
$T_j$ (max.)	150 °C

# 1 Characteristics

**Table 2. Absolute ratings (limiting values at  $T_{amb} = 25\text{ °C}$ , unless otherwise specified)**

Symbol	Parameter	Value	Unit
$V_{RRM}$	Repetitive peak reverse voltage	30	V
$I_F$	Continuous forward current	300	mA
$I_{FSM}$	Surge non repetitive forward current	$t_p = 10\text{ ms}$ Sinusoidal	A
$I_{FRM}$	Repetitive peak forward current, square wave	$T_A = 85\text{ °C}$ , $\delta = 0.1$	A
$P_D^{(1)}$	Power dissipation	SOT-323	225
		SOD-523	200
$T_{stg}$	Storage temperature range	-65 to +150	°C
$T_J$	Maximum operating junction temperature	150	°C
$T_L$	Maximum soldering temperature	260	°C

1. On epoxy printed circuit board with recommended pad layout

**Table 3. Thermal parameters**

Symbol	Parameter	Value	Unit
$R_{th(j-a)}$	Junction to ambient <sup>(1)</sup>	SOT-323	550
		SOD-523	600

1. On epoxy printed circuit board with recommended pad layout

**Table 4. Static electrical characteristics**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit	
$I_R^{(1)}$	Reverse leakage current	$T_j = 25\text{ °C}$	$V_R = 5\text{ V}$	-		0.5	$\mu\text{A}$
			$V_R = 10\text{ V}$	-		1	
			$V_R = 25\text{ V}$	-	0.65	3	
			$V_R = 30\text{ V}$	-		5	
		$T_j = 70\text{ °C}$	$V_R = 10\text{ V}$	-	7	20	
		$T_j = 85\text{ °C}$		-	18	50	
$V_F^{(2)}$	Forward voltage drop	$T_j = 25\text{ °C}$	$I_F = 0.1\text{ mA}$	-		240	$\text{mV}$
			$I_F = 1\text{ mA}$	-		300	
			$I_F = 10\text{ mA}$	-		375	
			$I_F = 30\text{ mA}$	-		430	
			$I_F = 100\text{ mA}$	-		500	
			$I_F = 200\text{ mA}$	-		580	
			$I_F = 300\text{ mA}$	-	530		

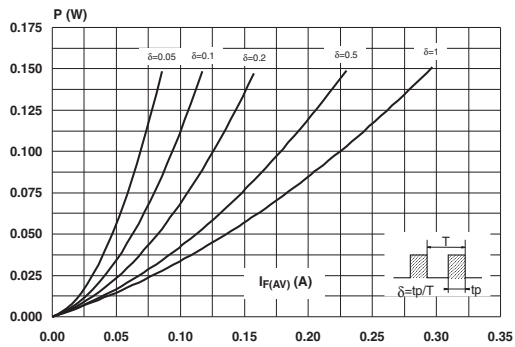
1. Pulse test:  $t_p = 5\text{ ms}$ ,  $\delta < 2\%$

2. Pulse test:  $t_p = 380\text{ }\mu\text{s}$ ,  $\delta < 2\%$

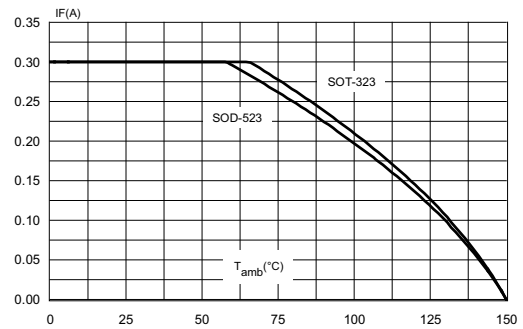
**Table 5. Dynamic characteristics**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C	Diode capacitance	$V_R = 0\text{ V}$ , $F = 1\text{ MHz}$	-	22	-	$\text{pF}$
		$V_R = 1\text{ V}$ , $F = 1\text{ MHz}$	-	14	-	
		$V_R = 10\text{ V}$ , $F = 1\text{ MHz}$	-	6	-	

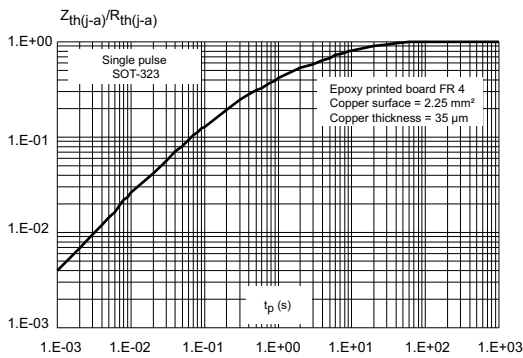
**Figure 1. Power dissipation versus average forward current**



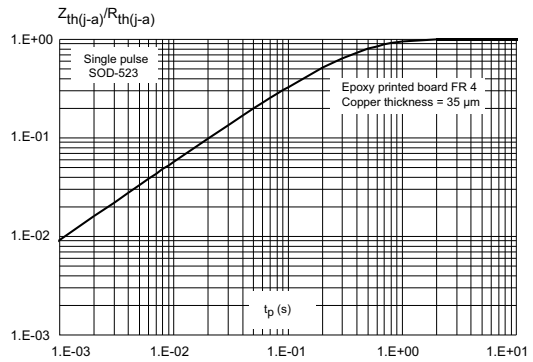
**Figure 2. Continuous forward current versus ambient temperature**



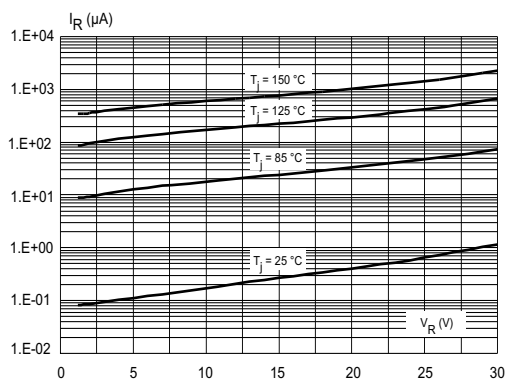
**Figure 3. Relative variation of thermal impedance junction to ambient versus pulse duration**



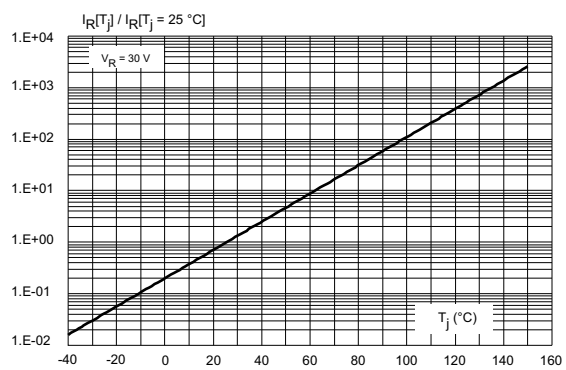
**Figure 4. Relative variation of thermal impedance junction to ambient versus pulse duration**



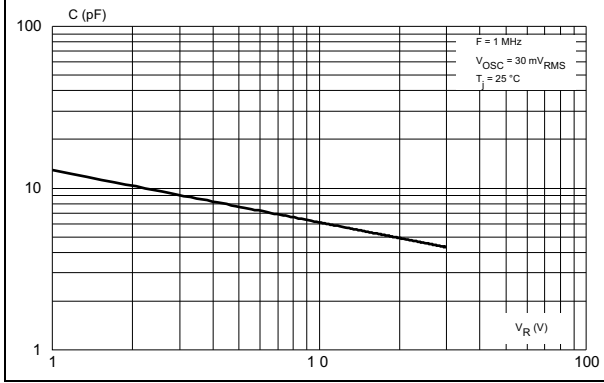
**Figure 5. Leakage current versus reverse applied voltage (typical values)**



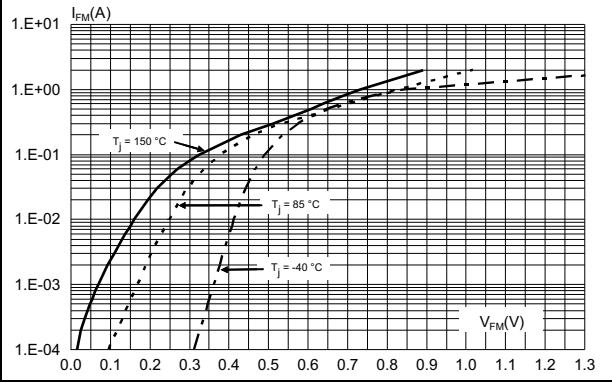
**Figure 6. Relative variation of reverse leakage current versus junction temperature (typical values)**



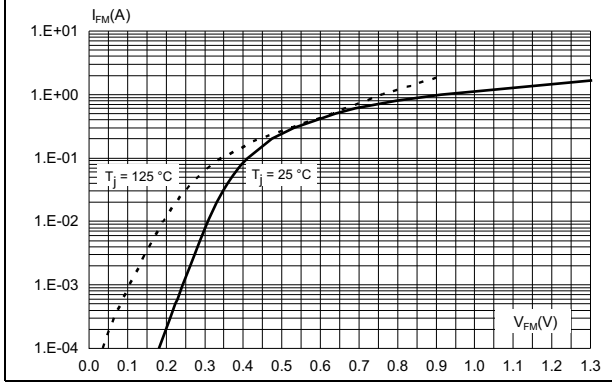
**Figure 7. Junction capacitance versus reverse applied voltage (typical values)**



**Figure 8. Forward voltage drop versus forward current (typical values)**



**Figure 9. Forward voltage drop versus forward current (typical values)**



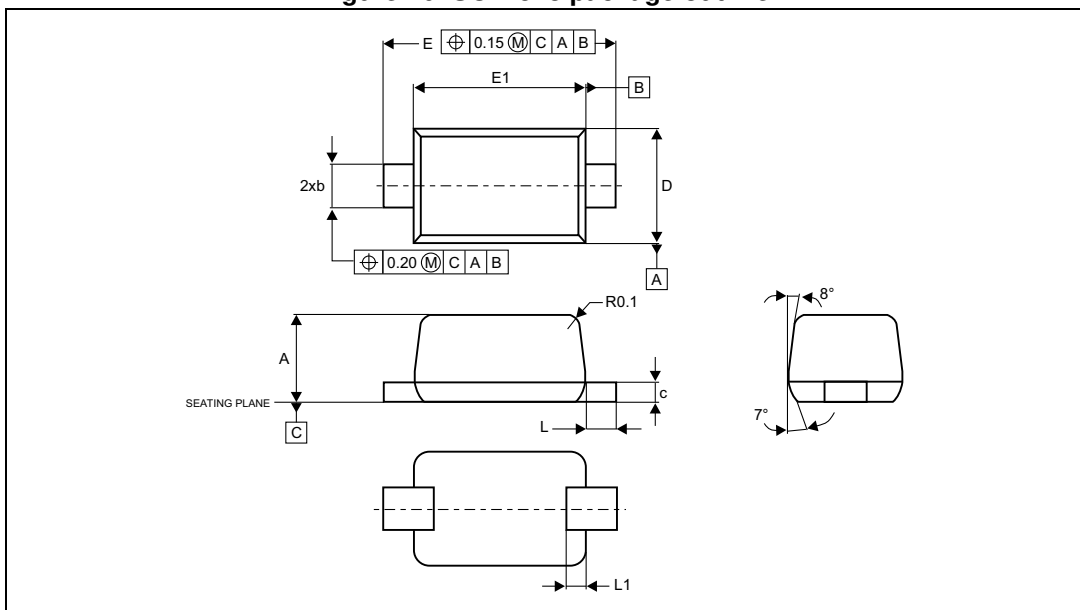
## 2 Package information

- Epoxy meets UL94, V0
- Lead-free packages

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

### 2.1 SOD-523 package information

Figure 10. SOD-523 package outline

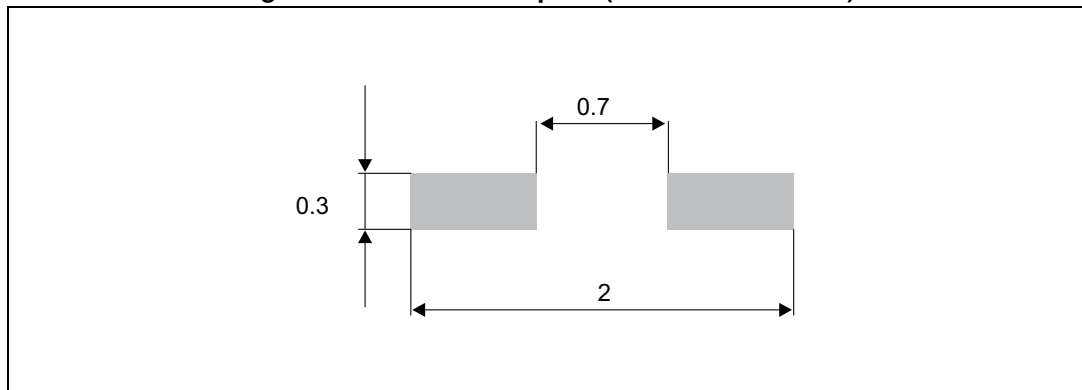


**Table 6. SOD-523 package mechanical data**

Ref.	Dimensions					
	Millimeters			Inches <sup>(1)</sup>		
	Typ.	Min.	Max.	Typ.	Min.	Max.
A	0.60	0.50	0.70	0.024	0.020	0.028
E	1.60	1.50	1.70	0.063	0.059	0.067
E1	1.20	1.10	1.30	0.047	0.043	0.051
D	0.80	0.70	0.90	0.031	0.028	0.035
b	-	0.25	0.35	-	0.010	0.014
c	-	0.07	0.20	-	0.003	0.008
L	0.20	0.15	0.25	0.008	0.006	0.010
L1	-	0.05	0.20	-	0.002	0.008

1. Values in inches are converted from mm and rounded to 4 decimal digits.

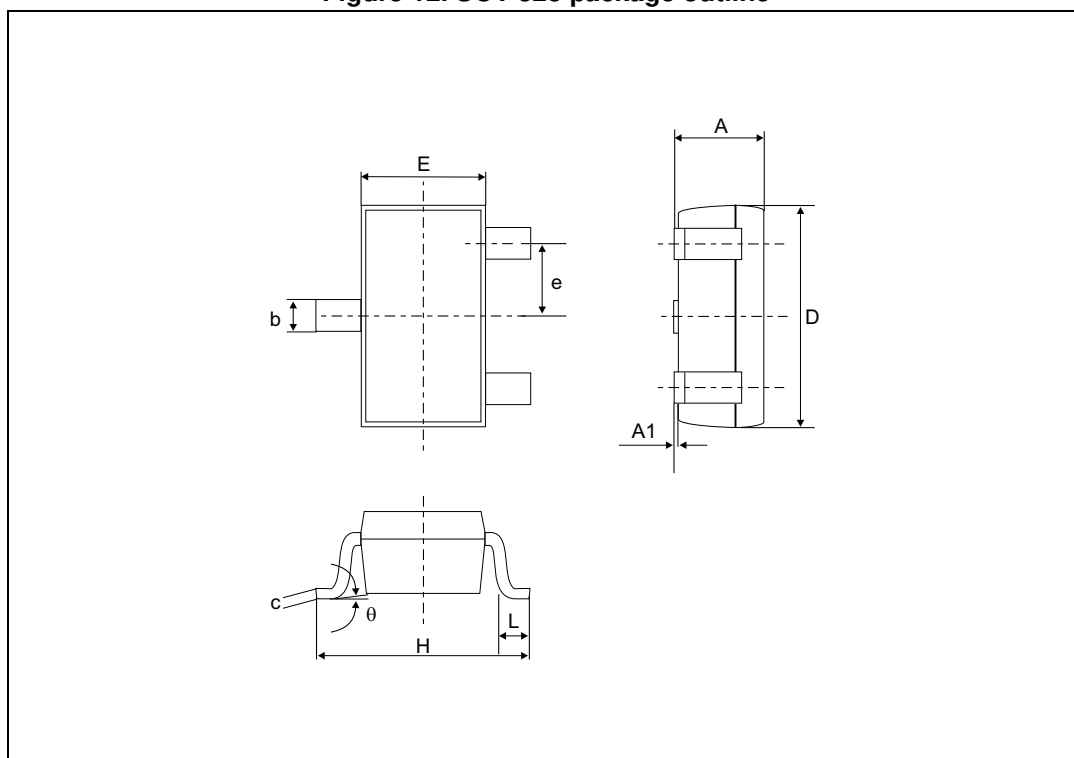
**Figure 11. SOD-523 footprint (dimensions in mm)**





## 2.2 SOT-323 package information

Figure 12. SOT-323 package outline

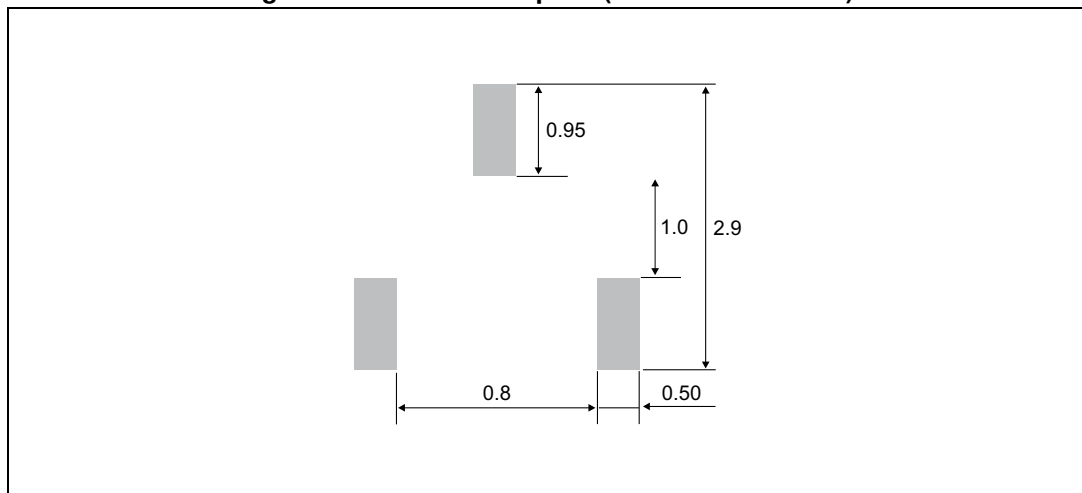


**Table 7. SOT-323 package mechanical data**

Ref.	Dimensions					
	Millimeters			Inches <sup>(1)</sup>		
	Typ.	Min.	Max.	Typ.	Min.	Max.
A	-	0.8	1.1	-	0.031	0.043
A1	-	0.0	0.1	-	0.0	0.004
b	-	0.25	0.4	-	0.010	0.016
c	-	0.1	0.26	-	0.004	0.010
D	2.0	1.8	2.2	0.079	0.071	0.086
E	1.25	1.15	1.35	0.049	0.045	0.053
e	0.65	-	-	0.026	-	-
H	2.1	1.8	2.4	0.083	0.071	0.094
L	0.2	0.1	0.3	0.008	0.004	0.012
q	-	0	30°	-	0	30°

1. Values in inches are converted from mm and rounded to 4 decimal digits.

**Figure 13. SOT-323 footprint (dimensions in mm)**

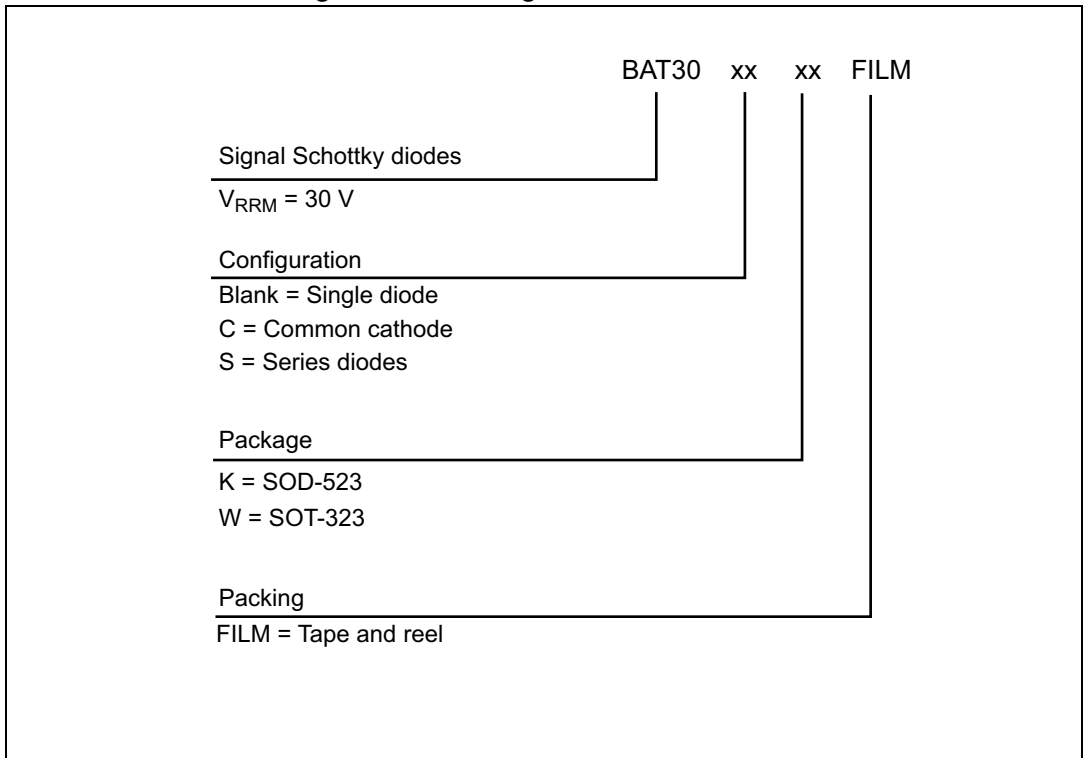


### 3 Ordering information

Table 8. Ordering information

Order code	Marking	Package	Weight	Base qty.	Packing mode
BAT30CWFILM	C30	SOT-323 Common cathode	6 mg	3000	Tape and reel
BAT30KFILM	30	SOD-523 Single	1.45 mg	3000	Tape and reel
BAT30SWFILM	S30	SOT-323 Serial	6 mg	3000	Tape and reel

Figure 14. Ordering information scheme



## 4 Revision history

**Table 9. Document revision history**

Date	Revision	Changes
24-Jul-2006	1	First issue
08-Jul-2009	2	Added SOD-923 package. Table 12 sorted on alphabetic sequence of order code. Updated ECOPACK statement.
13-Oct-2009	3	Updated <a href="#">Table 6</a> quote "L1" from 0.10 to 0.05.
01-Apr-2014	4	Added Pin 1 anode marker to SOT-666 package graphics. Updated <a href="#">Table 2: Absolute ratings (limiting values at <math>T_{amb} = 25\text{ °C}</math>, unless otherwise specified)</a> .
01-Apr-2015	5	Package information updated and removed: SOD-323, SOD-923, SOT-23 and SOT666. Updated cover page. Updated <a href="#">Table 2</a> and <a href="#">Table 3</a> . Updated <a href="#">Figure 14</a> and <a href="#">Figure 3</a> . Format updated to current standard.

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